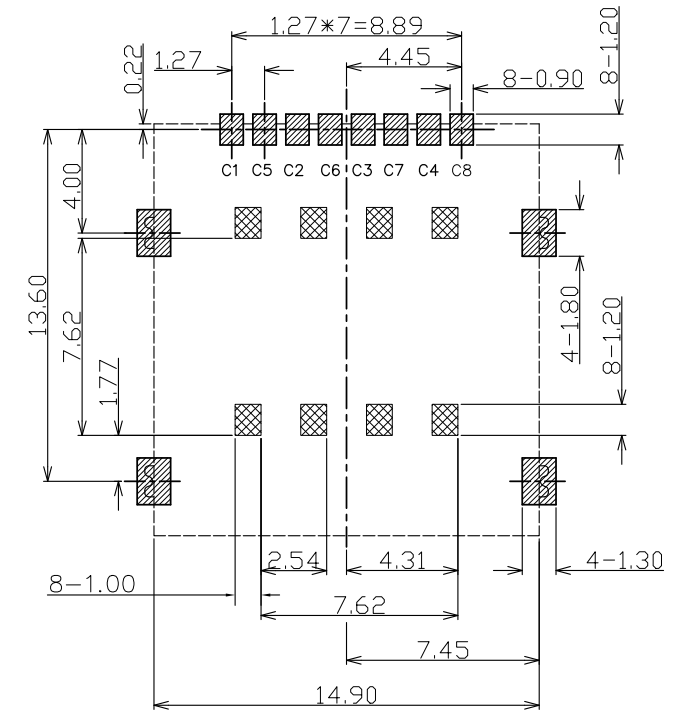
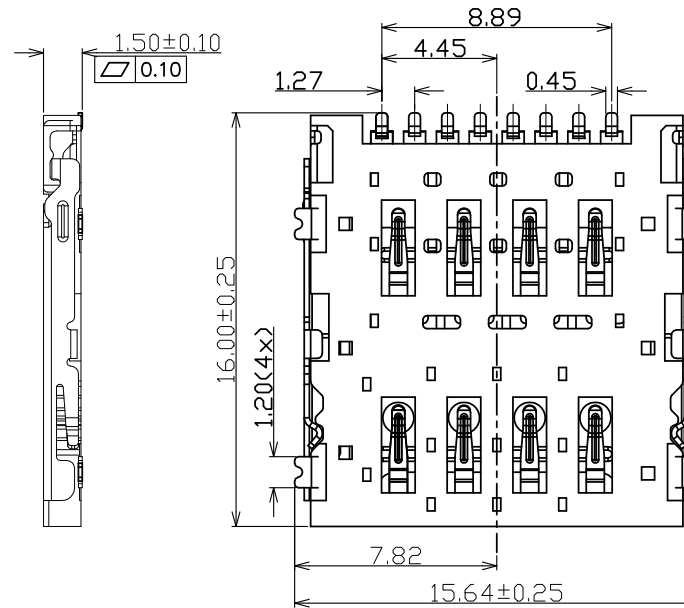
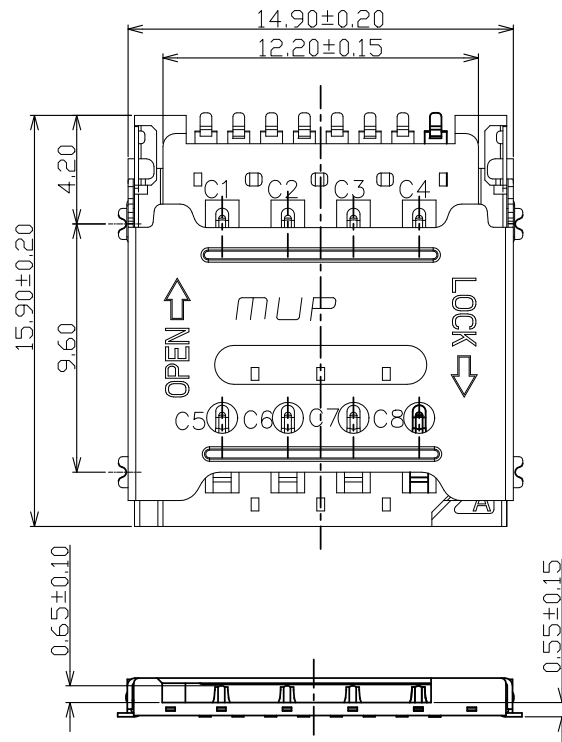
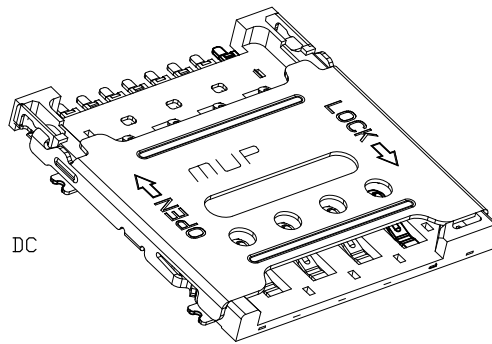


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ± 0.05)

TECHNICAL CHARACTERISTICS
1.General Characteristics
Dimensions:15.90LX14.90WX1.50H mm
Durability:5,000 cycles min.
2.Electrical Characteristics
Contact resistance:50m Ω typical,
100m Ω Max
Insulation resistance:>1000M/500V DC
3.Solderability
Vaporphase:215°C, 30sec.Max
IR reflow:260°C,5sec.Max
Manual soldering:370°C,3sec.Max
4.Environmental Characteristics
Operating remperature:-40°C~+85°C
Operating humidity:10%~+95%RH



Micro SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

- PAD AREA
 CONNECTOR OUTLINE
 NO PATTERN AND VIA HOLE IN THIS AREA

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	± 0.35	X*	$\pm 5^{\circ}$
X.X	± 0.25	X.X*	$\pm 4^{\circ}$
X.XX	± 0.15	X.XX*	$\pm 3^{\circ}$
X.XXX	± 0.10	X.XXX*	$\pm 2^{\circ}$

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **Micro-SIM Card Connector**

MODEL NO: **MUP-C791-3**

TYPE : **Hinge Type,8 PIN,H1.50mm(Short shell)**

PROJ.	UNIT	SCALE
	mm	1:1
CUSTOMER DRAWING		

DRAWN	DWG NO.:
CHECKED	DWG-MUP-C791-003
APPROVAL	SHEET
	1/1
	REVISION
	X1

